

In response to the Office Action, Applicants respectfully request that the above-identified application be amended as follows:

IN THE CLAIMS:

Please cancel Claims 2, 3, 23-30, 34-44, and 48-50 without prejudice or disclaimer of the subject matter presented therein.

Please amend Claims 1, 7, 9, 10, 12, and 31-33, and add new Claims 51-56, to read as shown below (a marked-up version of those claims, showing the changes made thereto, is attached):

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1. (Twice Amended) An electron beam apparatus comprising:

a first substrate that includes a plurality of electron-emitting devices, provided in a vacuum container;

a second substrate that is located opposite said first substrate and that has a region irradiated by electrons emitted by said electron-emitting devices in said vacuum container;

at least one spacer that is mounted as an atmospheric-pressure resistant structure, that is sandwiched directly between said first and second substrates, or indirectly via an intermediate member between said first and second substrates, and that is extended longitudinally in a direction perpendicular to the direction in which said first and second substrates are positioned opposite each other; and

a support member, for supporting said spacer outside an electron-emitting region that is defined between a region of said first substrate wherein said electron-emitting devices are located, and a region of said second substrate that is irradiated by said

electrons,

wherein said spacer has, in a vicinity of an end in a longitudinal direction, a portion shorter in a width direction of a gap between said first and second substrates rather than in another direction.

7. (Twice Amended) An electron beam apparatus comprising:

a first substrate that includes a plurality of electron-emitting devices, provided in a vacuum container;

a second substrate that is located opposite said first substrate and that has a region irradiated by electrons emitted by said electron-emitting devices;

at least one spacer that is mounted as an atmospheric-pressure resistant structure that is sandwiched directly between said first and second substrates, or indirectly via an intermediate member between said first and second substrates, and that is extended longitudinally in a direction perpendicular to the direction in which said first and second substrates are positioned opposite each other; and

a support member that, outside an electron-emitting region that is defined between a region of said first substrate wherein said electron-emitting devices are located and the region on said second substrate that is irradiated by said electrons, is mounted on said substrate whereon said spacer is provided so that said support member supports said spacer,

wherein said support member and said spacer are secured to each other, so that a direction in parallel to a mounting surface of said substrate on which said supporting member is mounted, is in parallel to a longitudinal direction of said spacer, and that a mapage of said spacer in a direction along which said first and second substrates are

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Concl'd

opposed to ~~each~~ other is straightened.

9. (Twice Amended) An electron beam apparatus comprising:

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a first substrate that includes a plurality of electron-emitting devices,  
provided in a vacuum container;  
a second substrate that is located opposite said first substrate and that has a  
region irradiated by electrons emitted by said electron-emitting devices;  
at least one spacer that is mounted as an atmospheric-pressure resistant  
structure, that is sandwiched directly between said first and second substrates, or indirectly  
via an intermediate member between said first and second substrates, and that is extended  
longitudinally in a direction perpendicular to the direction in which said first and second  
substrates are positioned opposite each other; and  
a support member, for supporting said spacer outside an electron-emitting  
region that is defined between a region of said first substrate wherein said electron-emitting  
devices are located, and a region of said second substrate that is irradiated by said  
electrons,  
wherein said spacer has a thermal expansion rate that is smaller than a  
thermal expansion rate of said substrate.

10. (Amended) An electron beam apparatus according to claim 9, wherein a  
difference between the thermal expansion ratio of said substrate and the thermal expansion  
ratio of said spacer does not exceed 5%.

B4 12. (Amended) An electron beam apparatus according to claim 11, wherein, while said support member is fixed to said spacer, said support member is fixed, to said substrate.

B5 31. (Amended) An electron beam apparatus according to claim 1, wherein said electron-emitting devices are connected by wiring laid on said first substrate, and a film formed on said spacer is electrically connected to said wiring.

C1 32. (Amended) An electron beam apparatus according to claim 7, wherein said electron-emitting devices are connected by wiring laid on said first substrate, and a film formed on said spacer is electrically connected to said first substrate by said wiring.

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23. (Amended) An electron beam apparatus according to claim 9, wherein said electron-emitting devices are connected by wiring laid on said first substrate, and a film formed on said spacer is electrically connected to said first substrate by said wiring.

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31. (New) An electron beam apparatus according to claim 1, wherein said spacer is fixed at a position at an end side thereof rather than said portion.

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32. (New) An electron beam apparatus according to claim 1, wherein said spacer has a section of which length in a direction along which said first and second substrates are opposed to each other is gradually made shorter in a

vicinity of the end of the longitudinal direction.

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cont.  
27  
53. (New) A method of manufacturing a structure comprising a first substrate, a second substrate, and a spacer extending against an atmospheric pressure, sandwiched directly or indirectly between said first and second substrates, the method comprising the steps of:

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fixing said spacer to a supporting member supporting said spacer in a state such that a mapage of said spacer is straightened;

disposing said spacer fixed to said supporting member onto said first substrate; and

disposing said first and second substrates in opposition to each other.

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54. (New) The method according to claim 27, wherein  
said step of fixing said spacer to said supporting member is conducted so that a direction in parallel to a mounting surface of said first substrate on which said supporting member is mounted is in parallel with a longitudinal direction of said spacer disposed on said first substrate, and a mapage of said spacer in a direction along which said first and second substrates are opposed to each other is straightened.

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55. (New) A method of manufacturing a structure comprising a first substrate, a second substrate and a spacer extending against an atmospheric pressure directly or indirectly between said first and second substrates, the method comprising the

steps of:

fixing said spacer to a supporting member supporting said spacer in a state such that said spacer is weighted;

disposing said spacer fixed to said supporting member onto said first substrate; and

disposing said second substrate in opposition to said first substrate.

3 <sup>3</sup> 56. (New) The method according to claim <sup>2</sup> 55, wherein

said step of fixing said spacer to said supporting member includes a process of weighting to said spacer in the direction along which said first and second substrates are opposed to each other.